SCAS186A - OCTOBER 1991 - REVISED APRIL 1996

- Members of the Texas Instruments Widebus™ Family
- Inputs Are TTL-Voltage Compatible
- Provide Extra Data Width Necessary for Wider Address/Data Paths
- Provide Inverted Data
- 3-State Outputs Drive Bus Lines or Buffer Memory Address Registers
- Flow-Through Architecture Optimizes PCB Layout
- Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise
- EPIC™ (Enhanced-Performance Implanted CMOS) 1-µm Process
- 500-mA Typical Latch-Up Immunity at 125°C
- Package Options Include Shrink Small-Outline 300-mil (DL) Package Using 25-mil Center-to-Center Pin Spacings and 380-mil Fine-Pitch Ceramic Flat (WD) Packages Using 25-mil Center-to-Center Pin Spacings

description

These 16-bit buffers/bus drivers provide a high-performance bus interface for wide data paths.

The 3-state control gate is a 2-input AND gate with active-low inputs so that if either output-enable (OE1 or OE2) input is high, all corresponding outputs are in the high-impedance state.

The 74ACT16540 is packaged in TI's shrink small-outline package, which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The 54ACT16540 is characterized for operation over the full military temperature range of –55°C to 125°C. The 74ACT16540 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE (each 8-bit section)

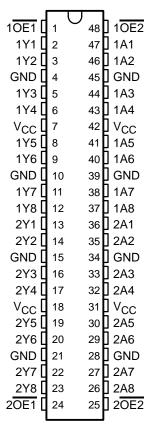
	INPUTS		OUTPUT
OE1	OE2	Α	Y
L	L	L	Н
L	L	Н	L
Н	X	Χ	Z
Х	Н	X	Z



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54ACT16540 . . . WD PACKAGE 74ACT16540 . . . DL PACKAGE (TOP VIEW)

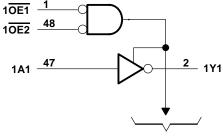


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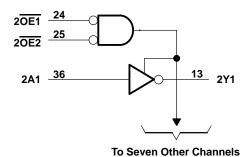
logic symbol†

10E1 48 EN1 10E2 24 20E1 EN2 25 2OE2 47 2 1Y1 1A1 1♡ 3 46 1Y2 1A2 5 44 1Y3 1A3 43 6 1A4 1Y4 41 8 1A5 1Y5 40 9 1A6 1Y6 38 11 1A7 1Y7 37 12 1A8 1Y8 36 13 2A1 2Y1 2♡ 35 14 2A2 2Y2 33 16 2A3 2Y3 32 17 2A4 2Y4 30 19 2A5 2Y5 29 20 2A6 2Y6 27 22 2A7 2Y7 26 23 2A8 2Y8

logic diagram (positive logic)



To Seven Other Channels



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V _{CC}	0.5 V to 7 V
Input voltage range, V _I (see Note 1)—C	$0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Output voltage range, V _O (see Note 1)–C	$0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$)	±20 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CC})	±50 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±50 mA
Continuous current through V _{CC} or GND	±400 mA
Maximum power package dissipation at T _A = 55°C (in still air) (see Note 2): DL package	1.2 W
Storage temperature range, T _{stg}	65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
 - 2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

recommended operating conditions (see Note 3)

		54ACT16540		74ACT16540			UNIT	
		MIN	NOM	MAX	MIN	NOM	MAX	UNII
VCC	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2		1/	2			V
V _{IL}	Low-level input voltage		Ž,	0.8			0.8	V
VI	Input voltage	0	PA	VCC	0		VCC	V
۷o	Output voltage	0	1:	VCC	0		VCC	V
ІОН	High-level output current		2	-24			-24	mA
loL	Low-level output current	02	0	24			24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0		10	0		10	ns/V
TA	Operating free-air temperature	-55		125	-40		85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V	T _A = 25°C			54ACT16540		74ACT16540		UNIT
PARAMETER	TEST CONDITIONS	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNII
		4.5 V	4.4			4.4		4.4		
	I _{OH} = -50 μA	5.5 V		5.4		5.4				
Voн	I _{OH} = -24 mA	4.5 V	3.94			3.8		3.8		V
	10H = -24 IIIA	5.5 V	4.94			4.8		4.8		
	$I_{OH} = -75 \text{ mA}^{\dagger}$					3.85		3.85		
	I _{OL} = 50 μA	4.5 V			0.1		0.1		0.1	
		5.5 V			0.1		0.1		0.1	
VOL	I _{OL} = 24 mA	4.5 V			0.36		0.44		0.44	V
		5.5 V			0.36	6	0.44		0.44	
	$I_{OL} = 75 \text{ mA}^{\dagger}$	5.5 V) ₇ c	1.65		1.65	
lj	V _I = V _{CC} or GND	5.5 V			±0.1	90	±1		±1	μΑ
loz	$V_O = V_{CC}$ or GND	5.5 V			±0.5	Q.	±5		±5	μΑ
Icc	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			8		80		80	μΑ
∆lcc [‡]	One input at 3.4 V, Other inputs at V _{CC} or GND	5.5 V			0.9		1		1	mA
C _i	V _I = V _{CC} or GND	5 V		4						pF
Co	V _O = V _{CC} or GND	5 V		13						pF

[†] Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.



[‡] This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

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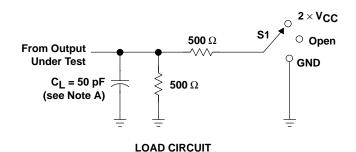
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER FROM TO		T,	չ = 25°C	;	54ACT	16540	74ACT	16540	UNIT	
PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
^t PLH	А	>	2.1	5.1	6.8	2.1	7.5	2.1	7.5	20
^t PHL	A	ī	3.9	6.8	8.5	3.9	9,5	3.9	9.5	ns
^t PZH	1	>	2.7	6.2	8	2.7	8.9	2.7	8.9	20
t _{PZL}	OE	ī	3.6	7.5	9.5	3.6	10.5	3.6	10.5	ns
^t PHZ	ŌĒ	V	5.4	9.2	10.9	5.4	11.9	5.4	11.9	
^t PLZ	OE	Ť	5.4	8.6	10.3	5.4	11.1	5.4	11.1	ns

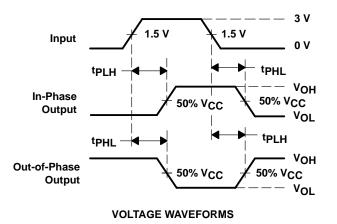
operating characteristics, V_{CC} = 5 V, T_A = 25°C

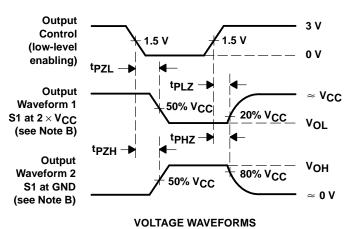
	PARAMETER		TEST CO	NDITIONS	TYP	UNIT
C _{pd} Power dissipation capacitance per buffer		Outputs enabled	C _I = 50 pF,	f = 1 MHz	42	ηE
Cpd	rower dissipation capacitance per buller	Outputs disabled	CL = 50 pr,	I = I IVIMZ	8.5	ρг

PARAMETER MEASUREMENT INFORMATION



TEST	S 1
tPLH/tPHL	Open
tPLZ/tPZL	2×V _{CC}
tPHZ/tPZH	GND





NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_O = 50 Ω , t_f = 3 ns, t_f = 3 ns.
- D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

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